OIPE JC139
MAY 13 2002
PATENT & TRADEMARK OFFICE

05-16-2002

102092297

PATENT

IN THE UNIT 102092297 **EMARK OFFICE**

REQUEST FOR ASSIGNMENT RECORDAL

Box Assignments
Honorable Commissioner of Patents and Trademarks
Washington, D.C. 20231

Dear Sir:

5-13-02

Please record the attached assignment document.

1. Names of conveying parties: Sakari TADA
Eietsu HASEGAWA

2. Name and address of receiving party:
SENJU METAL INDUSTRY CO., LTD.
23 Senju-Hashido-cho
Adachi-ku, Tokyo, Japan

3. Nature of conveyance: Assignment
Execution Date: April 22, 2002 for TADA
April 23, 2002 for HASEGAWA

4. Application No.: 10/103,572
The execution dates of the patent application are April 22, 2002 for TADA and April 23, 2002 for HASEGAWA.

5. Name and address of party to whom correspondence concerning the attached document should be mailed:

05/15/2002 DBYRNE 00000158 10103572
01 FC:581 40.00 OP

1034

Michael Tobias
#40
1717 K Street N.W., Suite 613
Washington, D.C. 20036

6. Total number of patent applications involved: 1

7. Total fee: $40.00

[X] Enclosed
[ ] Authorized to be charged to the deposit account
[X] The Commissioner is authorized to charge any deficiencies in the fee payment accompanying this communication and to credit any excess payment of fees to Deposit Account No. 50-1079.

8. Statement and signature
To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

May 11, 2002
Date

Michael Tobias

Michael Tobias
Registration No. 32,948

Total number of pages comprising cover sheet, attachments and document: 4

ASSIGNMENT

WHEREAS, We, Sakari TADA and Eietsu HASEGAWA, residing in Yokohama-shi, Kanagawa, Japan and Satte-shi, Saitama, Japan, respectively, have invented certain new and useful improvements entitled

METHOD OF RECOVERING LEAD-FREE SOLDER FROM PRINTED CIRCUIT BOARDS

(a) for which an application for United States Letters Patent was filed on
March 22, 2002
and identified by United States Serial No. 10/103,572 ; or

(b) for which an application for United States Letters Patent was executed on
________________________________,

AND, WHEREAS, SENJU METAL INDUSTRY CO., LTD. , a corporation of Japan, having a place of business at 23 Senju-Hashido-cho, Adachi-ku, Tokyo, Japan , hereinafter called the "assignee", is desirous of acquiring the entire right, title, and interest in and to said application and the inventions and improvements therein disclosed.

NOW, THEREFORE, in consideration of One ($1.00) Dollar and other good and valuable consideration paid to us by said assignee, the receipt of which is hereby acknowledged, we do hereby assign, sell, transfer, and set over unto said assignee the entire right, title and interest in and to said application and the inventions and improvements therein disclosed for the United States and all foreign countries and any Letters Patent which may issue therefor in the United States and all foreign countries and all divisions, reissues, continuations, renewals, and/or extensions thereof, said assignee to have and to hold the interests herein assigned to the full ends of the terms of said Letters Patent and any and all divisions, reissues, continuations, renewals, and/or extensions thereof, respectively, as fully and entirely as the same would have been held and enjoyed by us had this assignment not been made.

The Commissioner of Patents and Trademarks is requested to issue such Letters Patent in accordance herewith. We covenant that we are the lawful owners of the said application, inventions, and improvements, that the same are unencumbered, that no license has been granted to make, use, or vend the said inventions or improvements or any of them, and that we have the full right to make this assignment.

And for the consideration aforesaid, we agree jointly and individually that we will communicate to said assignee or the representatives thereof any facts known to us respecting said inventions and improvements, and will, upon request, but without expense to us, testify in any legal proceedings, sign all lawful papers, execute all divisional, reissue, continuation, renewal, and/or extension applications, make all rightful oaths, and generally do all other and further lawful acts, deemed necessary or expedient by said assignee or by counsel for said assignee, to assist or enable said assignee to obtain and enforce full benefits from the rights and interests herein assigned. This assignment shall be binding upon our heirs, executors, administrators, and/or assigns, and shall inure to the benefit of the heirs, executors, administrators, successors, and/or assigns, as the case may be, of said assignee.

We authorize the assignee and its agents to insert or to have inserted in this instrument the execution date/or the filing date and serial number of our patent application.

Dated: april 22. 2002

Sakari Tada
Sakari TADA

Dated: April 23, 2003

Eietsu Hasegawa
Eietsu HASEGAWA